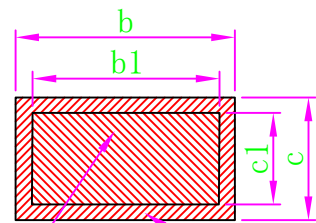


DETAILED: F



BASE METAL
WITH PLATING
SECTION B-B

Note:

1. All dimension are in mm.
2. Dim D & E1 does not include plastic flash;
Flash: Plastic residual around body edge after
dejunk/singulation.
3. Dim b does not include dambar protrusion/intrusion.
4. Plating thickness 0.007mm-0.015mm

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	-	-	1.70
A1	0.10	0.15	0.20
A2	1.30	1.40	1.50
b	0.18	-	0.26
b1	0.17	0.20	0.23
c	0.13	-	0.17
c1	0.12	0.13	0.14
D	6.90	7.00	7.10
E	8.80	9.00	9.20
eB	8.10	-	8.28
E1	6.90	7.00	7.10
e	0.50 BSC		
L	0.42	0.57	0.72
L1	0.90	1.00	1.10
θ	0	-	10°



拟制		复审	
审核		会签	
制图		标准化	
幅面: A4		批准	
		比例: 1:1	

更改标记	更改内容	签 名	日 期	
<div><div><div><div></div><div></div><div></div><div></div></div><div>永嘉微电</div><div>Vinka Microelectronics</div></div></div>				
VKXHLQFP48V11_POD 产品外形图名称		图 号:VKXHLQFP48V11_POD		
		单 位	版本	密 级
		mm	V1.1	
		第 1 张	共 1 张	
<div><div><div></div><div></div></div><div>-</div><div><div></div><div></div></div></div>				